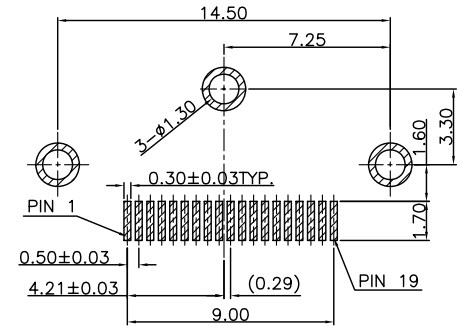
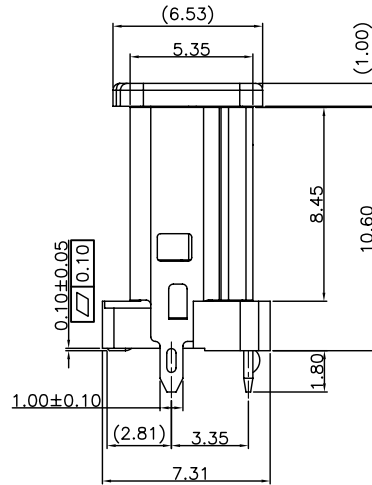
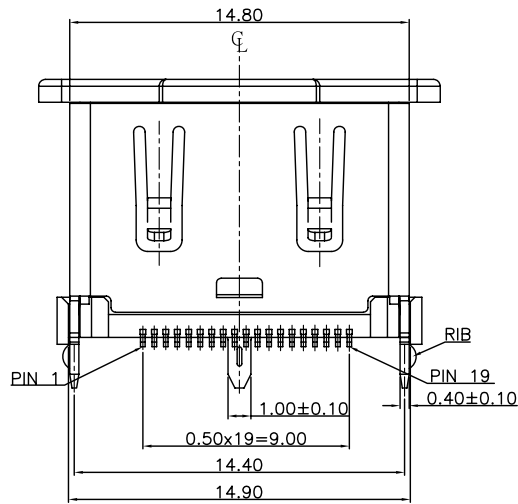


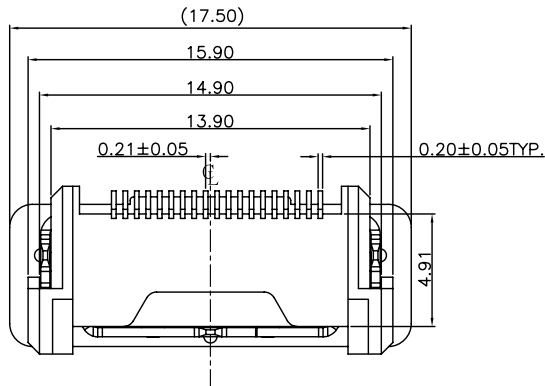
NOTES:

1. MATERIAL:
    - 1.1 HOUSING: HIGH TEMPERATURE THERMOPLASTIC  
UL 94V-0 RATED, BLACK
    - 1.2 CONTACT: COPPER ALLOY
    - 1.3 SHELL: COPPER ALLOY/SPCC
  2. PLATING:
    - 2.1 CONTACT:  
GOLD PLATED OVER NICKEL
    - 2.2 SHELL:  
NICKEL PLATED
  3. P/N: HHF-33X001-XSE
- TERMINAL PLATING CODE: \_\_\_\_\_ REV. CODE
- A: CONTACT AREA: GOLD FLASH  
SOLDER AREA: MATTE TIN 100u"
- B: CONTACT AREA: 3u" GOLD  
SOLDER AREA: MATTE TIN 100u"
- C: CONTACT AREA: 15u" GOLD  
SOLDER AREA: MATTE TIN 100u"



**RECOMMENDED PCB LAYOUT THICKNESS = 1.6 mm**

**TOLERANCE = ±0.05**  
**(TOP VIEW)**



MATERIAL	TOLERANCE UNSPECIFIED	<b>ZheJiang HeFeng Technology Co.,Ltd</b>	SCALE	UNIT
	0.0 ±0.30 0° ±2°		1:1	mm
	0.00 ±0.20 .0° ±1°		NAME	
	0.000 ±0.10 .0° ±0.5°		HDMI A/F 朝天式 SMT TYPE(无外壳) (HSB-1)	
FINISH	DRAWN		SHEET	
	Chu 11/03/02		1/2	
	DESIGNER		DRAWING NO.	
	Chu 11/03/02		HHF-33X001-XSB	
CHECKED	REV		A	
APPROVED				

A	新版发行	chu	2011-03-02
Rev. 版本	CHANGE DESCRIPTION 变更内容	REVISOR 制/修订人	DATE 日期